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Preface

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Preface

This issue of the Journal of Physics: Conference Series contains the proceedings of the 2nd International Conference on Electronic Information and Mechanical Manufacturing (EIMM 2022). The conference took place in Guilin, China during November 18th-20th, 2022 (virtual conference), with the attendance of about 150 prominent delegates in the fields related to electronic information and mechanical manufacturing all over the world.

The electronic information engineering profession is pivotal in the development of China's information technology industry, and in the information age, the integration of big data, artificial intelligence, and the Internet of Things with the manufacturing industry is also deepening, leading to the constantly changing and upgrading of machinery manufacturing industry in the direction of automation and intelligence. EIMM 2022 created an international academic forum for scholars, specialists and researchers to present their research activities, exchange insights and new ideas, and discuss the key challenges and research directions facing the development of relative fields.

To make this conference on schedule, we had a three-part plenary conference including a keynote speech part delivered by three speakers from different countries. Among them, Prof. Yaping Zhao from Northeastern University, China performed a dramatic keynote speech. His research domains lie in Meshing Theory for Mechanical Transmissions, Research and Development of Novel Types of Gear Drive, Engineering Differential Geometry and so on. He published more than 30 papers in the international SCI journals as corresponding or first author, and won many academic titles like New Century Excellent Talent Awarded by Chinese Ministry of Education, Excellent Talent in Institutions of Higher Learning in Liaoning Province, Jianlong specially-appointed professor of Northeastern University China, etc. We are very optimistic that all participants will acquire new ideas and knowledge from this conference and each keynote speech to enhance the capability toward electronic information and mechanical manufacturing.

We have received tremendous paper submissions from all over China and abroad. Through a rigorous peer-review process, all submissions were performed double blind review to check their quality of content, level of innovation, significance, originality and legibility. Based on the expertise review comments, some excellent papers were accepted and the corresponding authors were invited to submit their papers for final publication. The accepted papers included topics on: Electronic Information Engineering, Flexible Electronics, Numerical Control Technology, Industrial Engineering Technology, etc.

We would like to thank the Conference General Chairs and the Technical Program Committees for their hard work that lead to the organization of this event, to the members of the Journal of Physics: Conference Series for their patience while waiting for the final versions of the papers and to every author who has contributed with an article to these proceedings. We firmly believe that all the attendees have had fruitful discussions and gained valuable knowledge, and will enjoy the opportunity for future collaborations.

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